

SMD ■ Top View LEDs 67-21-YSC-C2U2AABPE-2T8-AM



Features

- RoHS compliant.
- P-LCC-2 package.
- Wide viewing angle 120°.
- Colorless clear resin.
- Brightness: 527 to 713mcd at 20mA
- Inner reflector and white package.
- Precondition: Bases on JEDEC J-STD 020D Level 3.
- Qualification according to AEC-Q101 rev C.
- Useable in severe lead free processes with automotive reflow profile (IR reflow or wave soldering)

Applications

- Automotive backlighting or indicator: Dashboard, switch, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- Optical indicator.
- General applications.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Orange	Water Clear

Absolute Maximum Ratings (Ta=25 °C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	10	V
Forward Current	I_F	50	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	200	mA
Power Dissipation	P_d	200	mW
Junction Temperature	T_j	115	
Operating Temperature	T_{opr}	-40 ~ +100	
Storage Temperature	T_{stg}	-40 ~ +110	
Thermal Resistance	$R_{th\ J-A}$	250	K/W
	$R_{th\ J-S}$	150	K/W
ESD (Classification acc. AEC Q101)	ESD_{HBM}	2000	V
	ESD_{MM}	200	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 for 30 sec. Hand Soldering : 350 for 3 sec.	

Electro-Optical Characteristics (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_v	527	---	713	mcd	$I_F = 20\text{mA}$
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	$I_F = 20\text{mA}$
Peak Wavelength	λ_p	---	591	---	nm	$I_F = 20\text{mA}$
Dominant Wavelength	λ_d	587.5	---	592.5	nm	$I_F = 20\text{mA}$
Spectrum Radiation Bandwidth	$\Delta\lambda$	---	15	---	nm	$I_F = 20\text{mA}$
Forward Voltage	V_F	1.75	---	2.55	V	$I_F = 20\text{mA}$
Reverse Current	I_R	---	---	10	μA	$V_R = 10\text{V}$

Note:

1. Tolerance of Luminous Intensity: $\pm 11\%$
2. Tolerance of Dominant Wavelength: $\pm 1\text{nm}$
3. Tolerance of Forward Voltage: $\pm 0.1\text{V}$

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
C	527	713	mcd	$I_F = 20\text{mA}$

Note:

Tolerance of Luminous Intensity: $\pm 11\%$

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
Y	587.5	590	nm	I _F =20mA
R	590	592.5		

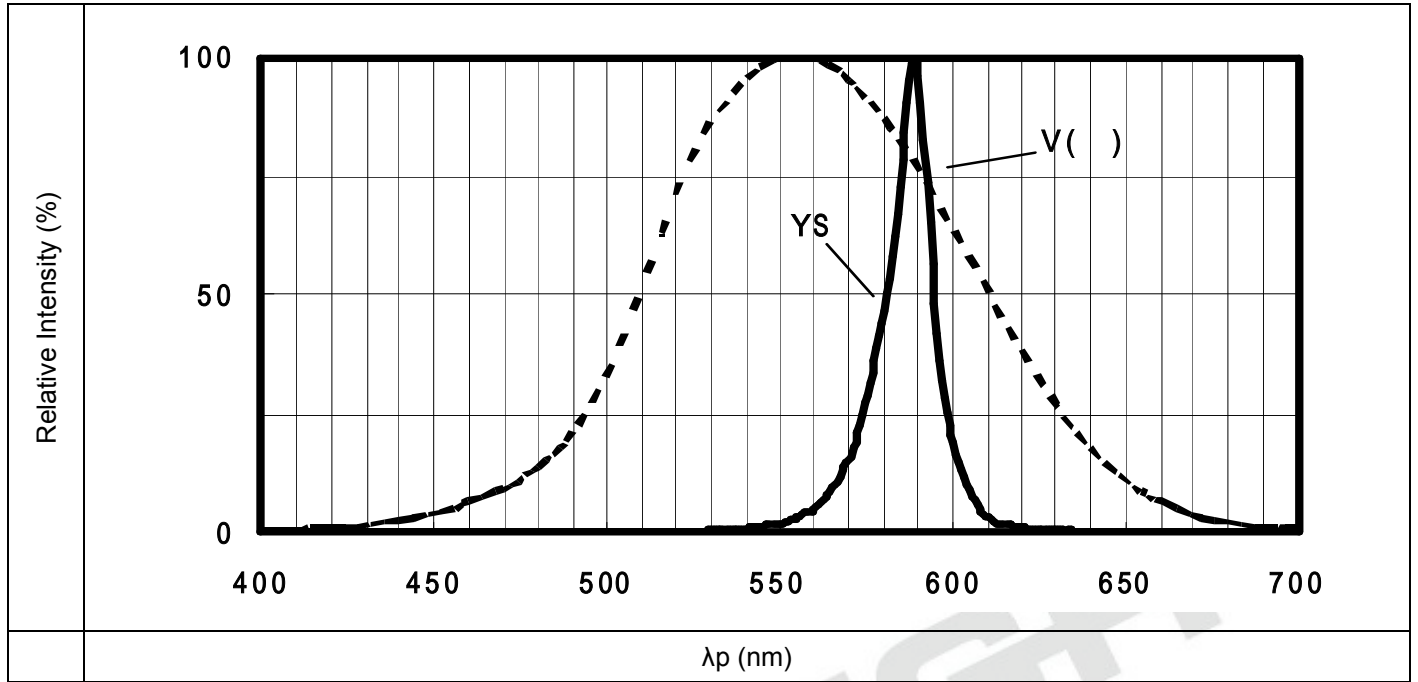
Note:

Tolerance of Dominant Wavelength: ±1nm

EVERLIGHT

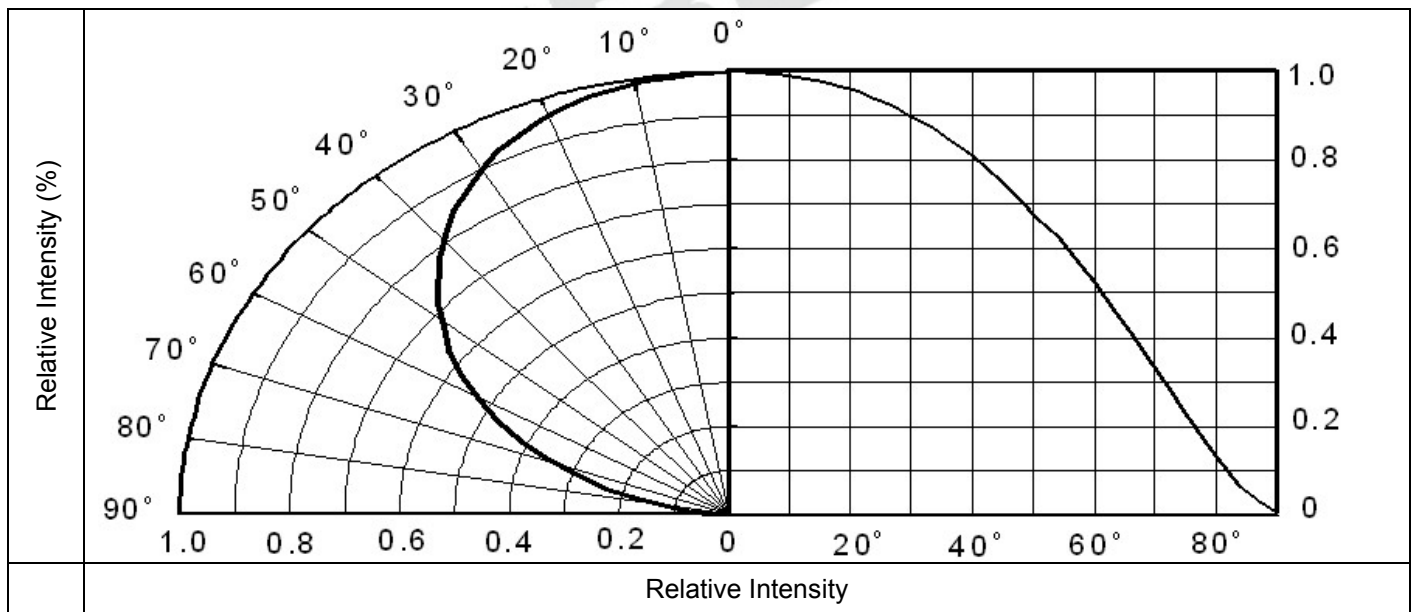
Typical Electro-Optical Characteristics Curves

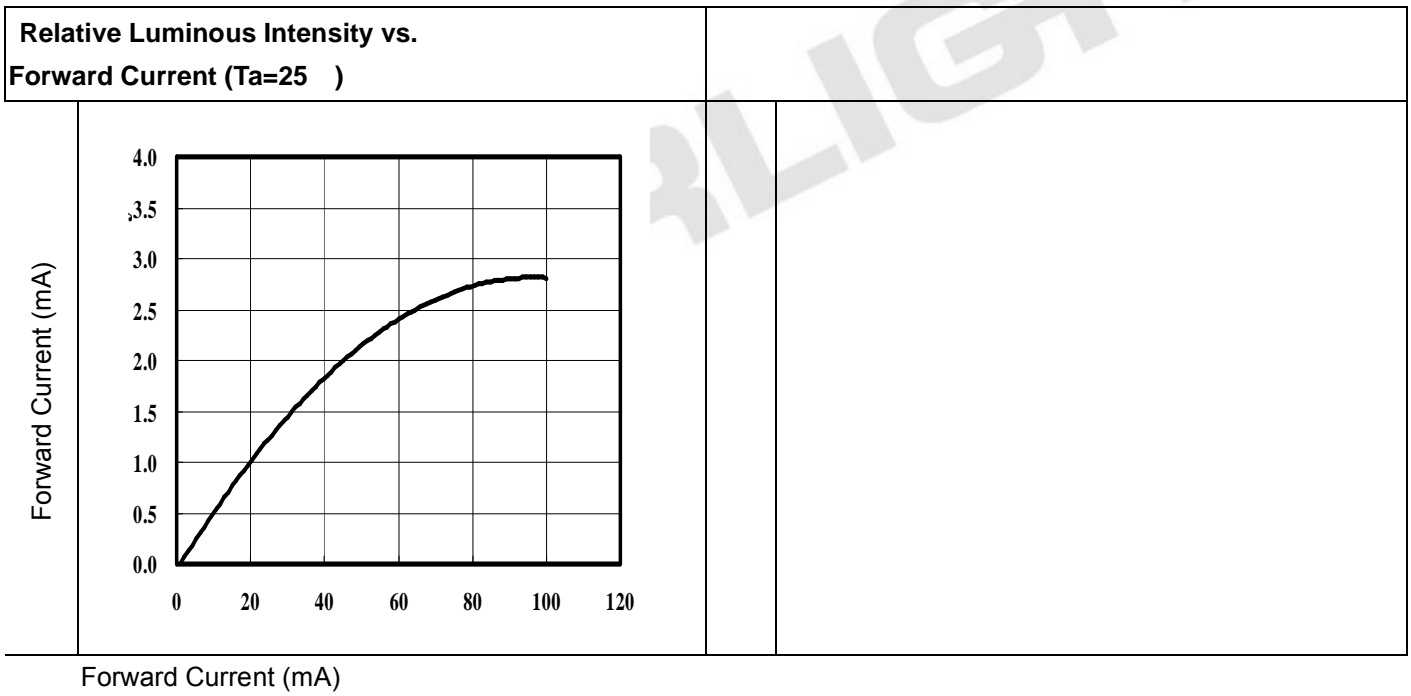
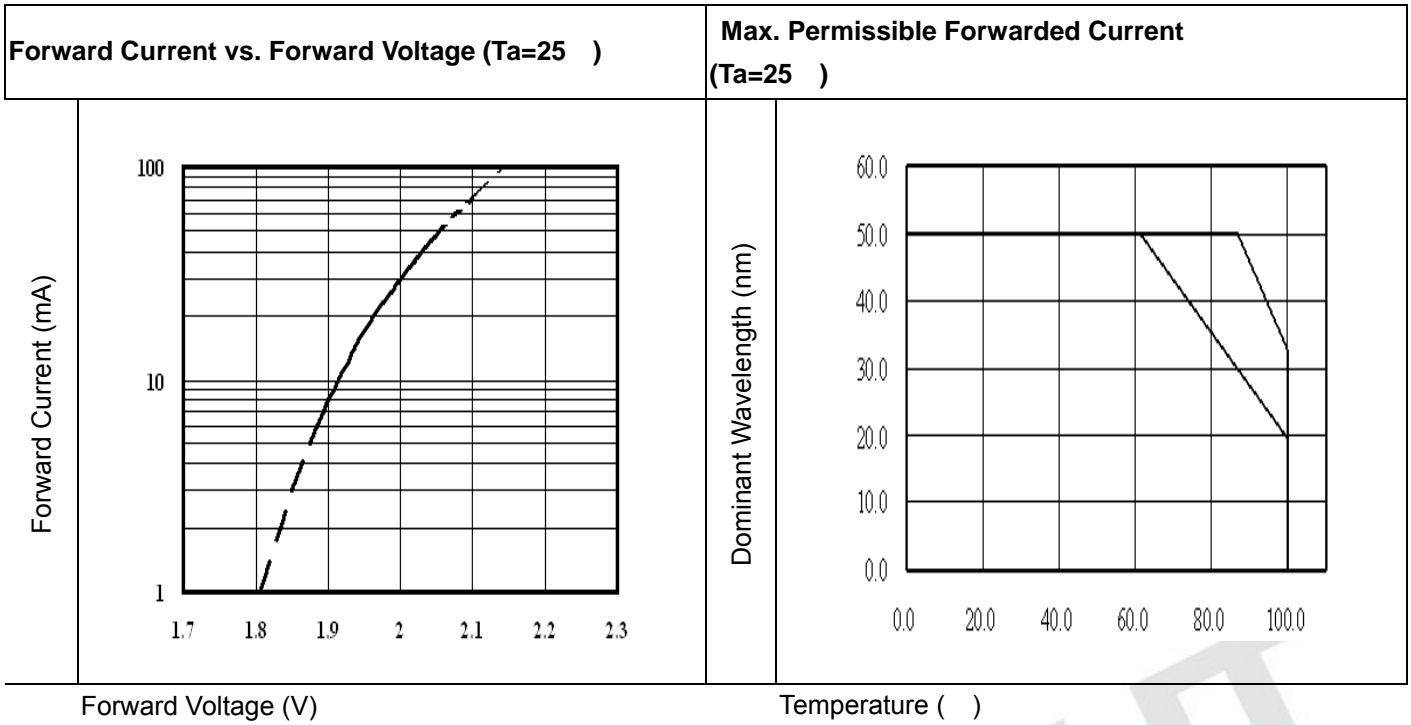
Typical Curve of Spectral Distribution



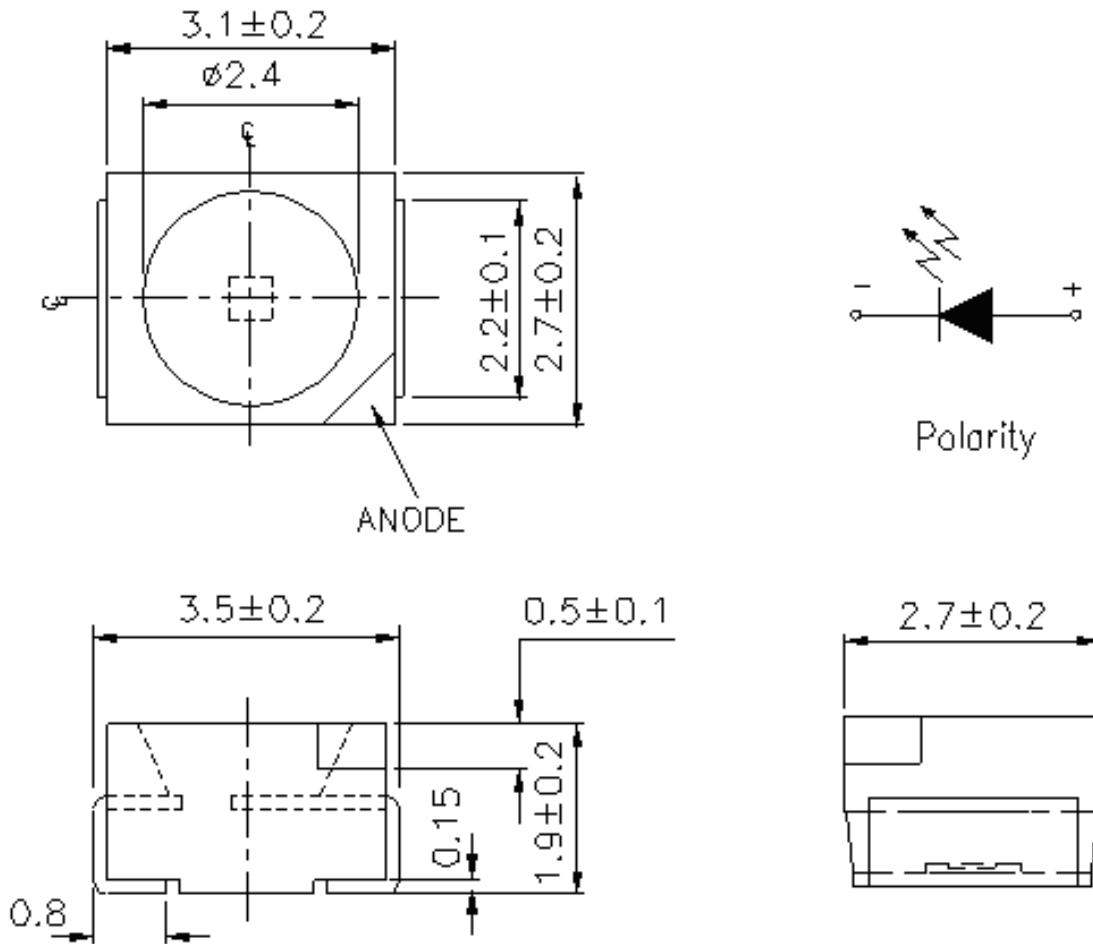
Note: $V(\lambda)$ =Standard eye response curve; $I_F = 20\text{mA}$

Diagram Characteristics of Radiation





Package Dimension



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

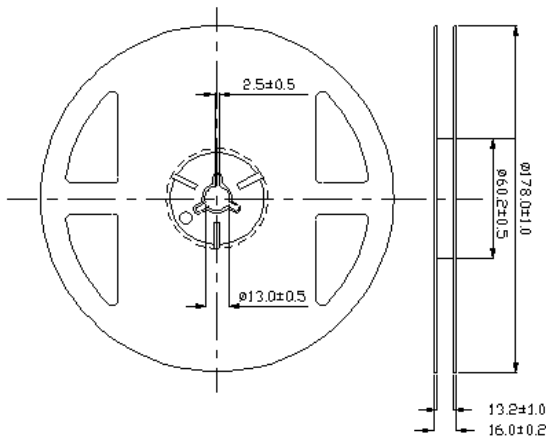
Moisture Resistant Packing Materials

Label Explanation

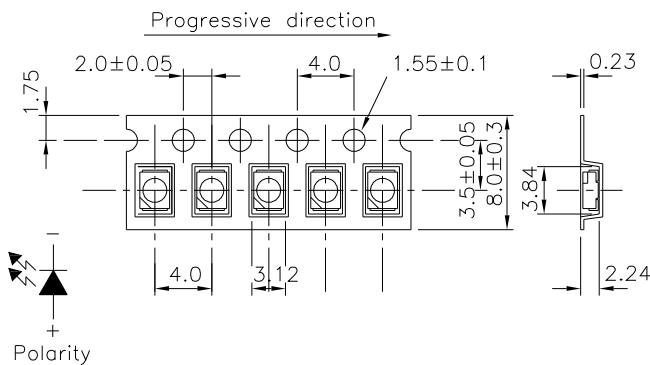


- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions

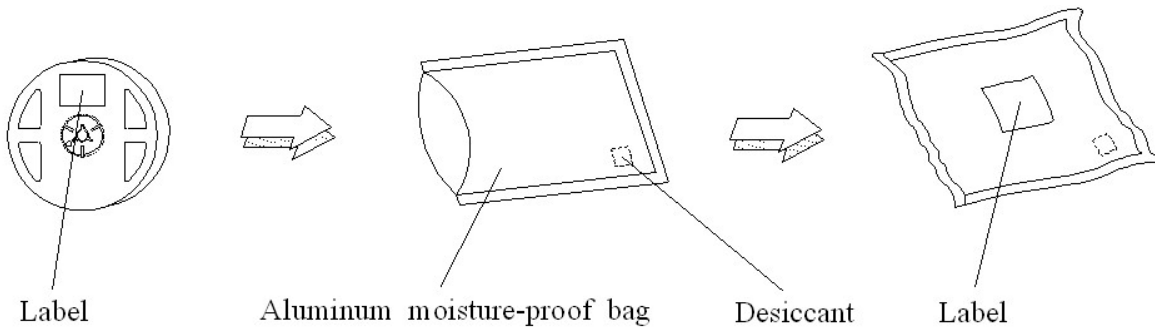


Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process

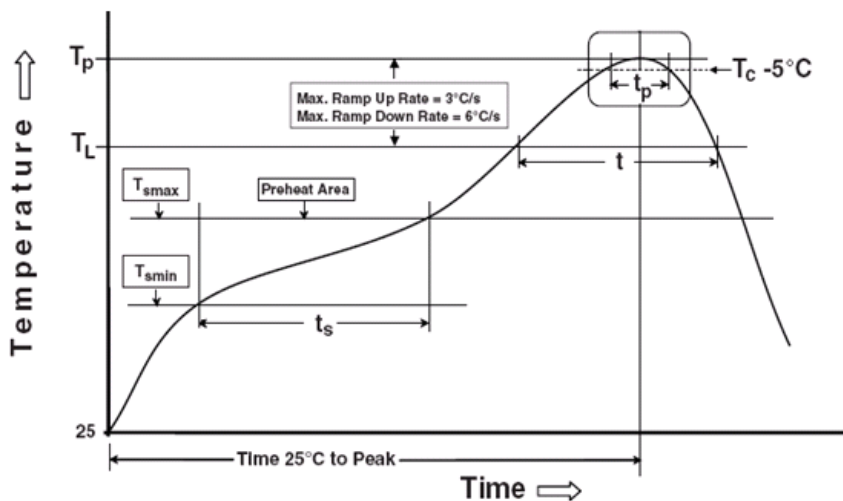


Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

Precautions for Use

Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Preheat

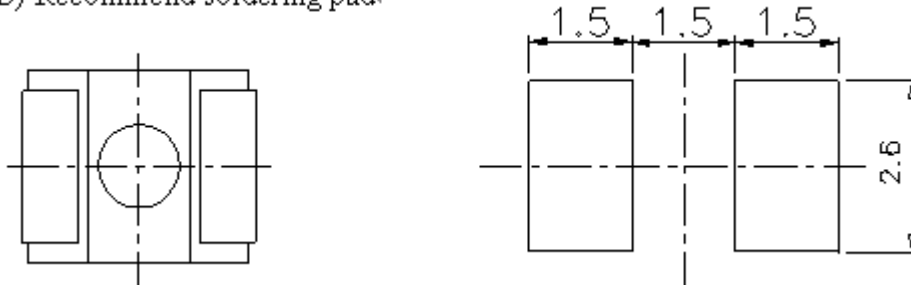
Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-150 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

All parameters are maximum body case temperature values and cannot be considered as a soldering profile. The body case temperature was measured by soldering a thermal couple to the soldering point of LEDs.

(B) Recommend soldering pad



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

- 3.1 Moisture proof bag should only be opened immediately prior to usage.
- 3.2 Environment should be less than 30 °C and 60% RH when moisture proof bag is opened.
- 3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350 °C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.